



Catálogo

SM-8160



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- Patented design, close-touch ultrasonic + spray cleaning, the stencil does not need to be soaked
- The ultrasonic source is 1-2.5mm away from the stencil, and the cleaning fluid flows from the gap and scans up and down to avoid blind area
- The stencil is quickly dried by the high-pressure nozzle during the lifting process, which solves the drying issue of water-based cleaning
- Quickly and efficiently clean the micro-printing leak holes of the stencil and the solder paste and glue in the printing area
- Cleaning cycle: solder paste, about 10 minutes; glue, less than 15 minutes
- PLC control, two modes, simple button operation, safe and reliable, easy maintenance
- Designed for MPC cleaning technology, equipped with circulating filtration system, low operating cost and environmental protection